

FIG. 1A

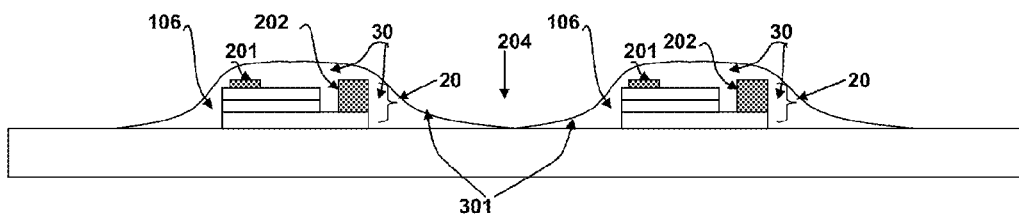


FIG. 1B

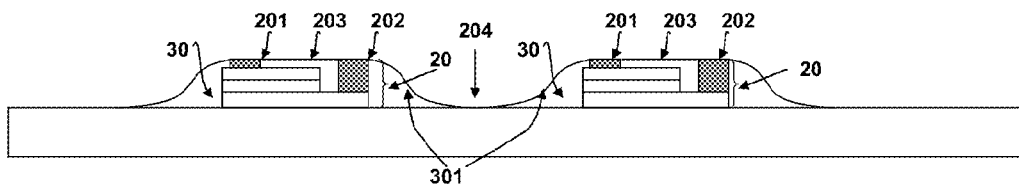


FIG. 1C

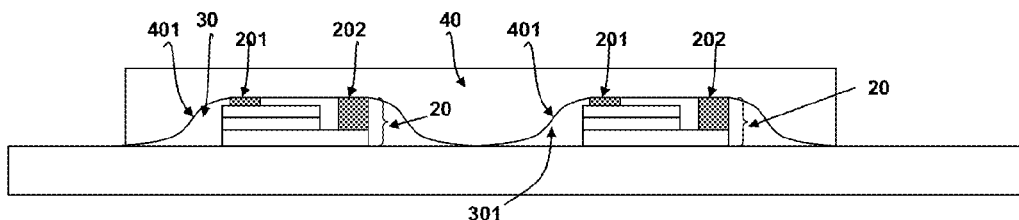


FIG. 1D

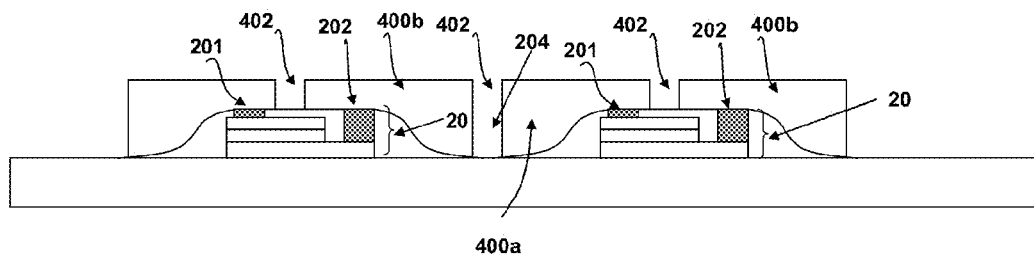


FIG. 1E

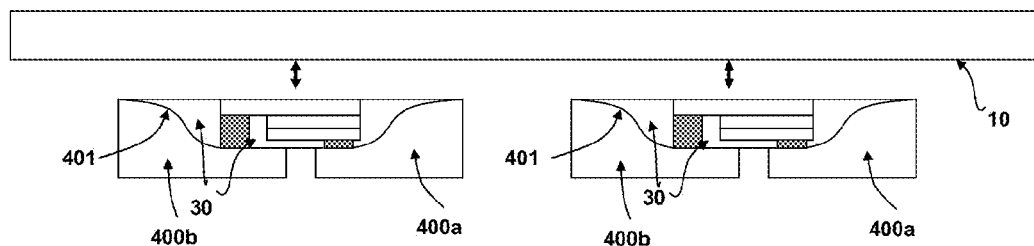


FIG. 1F

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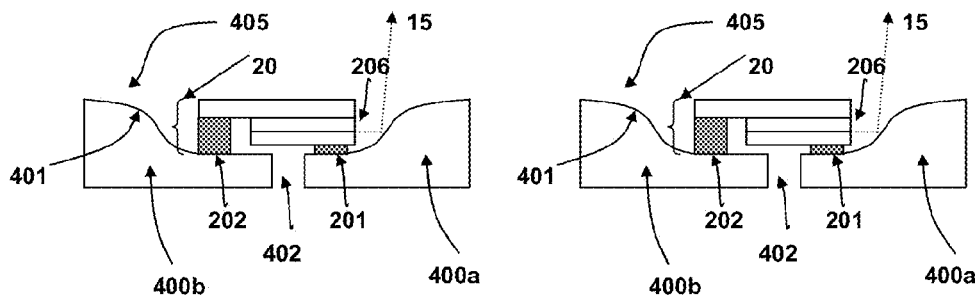


FIG. 1G

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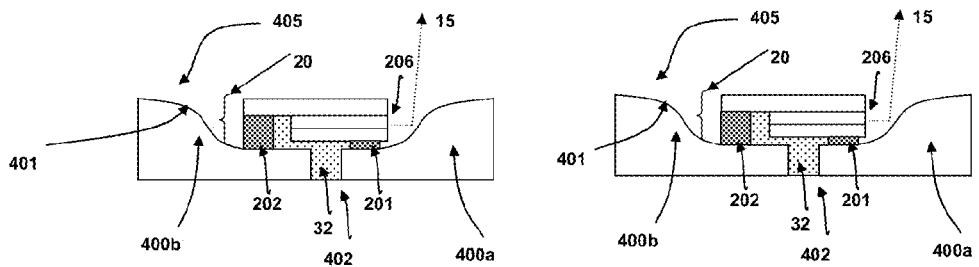


FIG. 1H

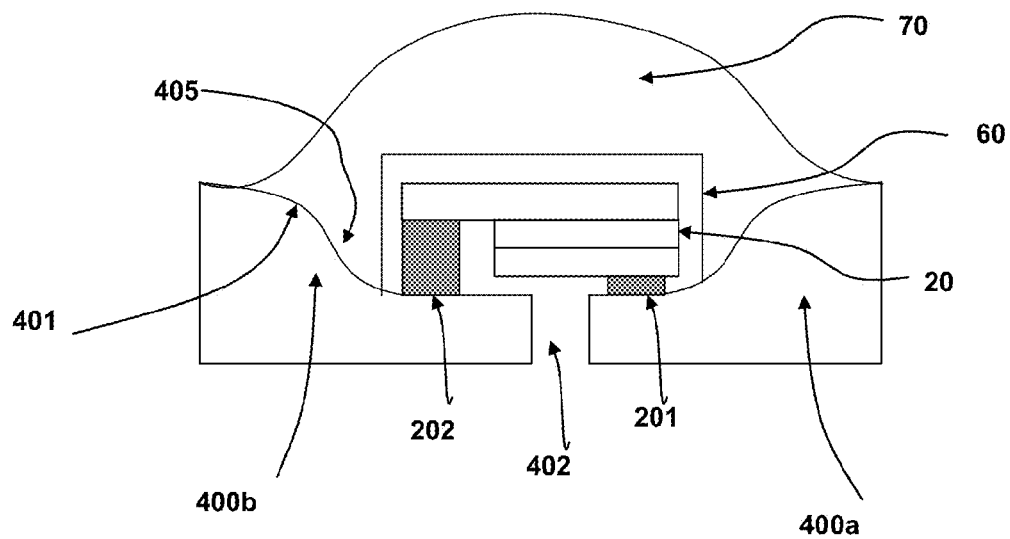


FIG. 2A

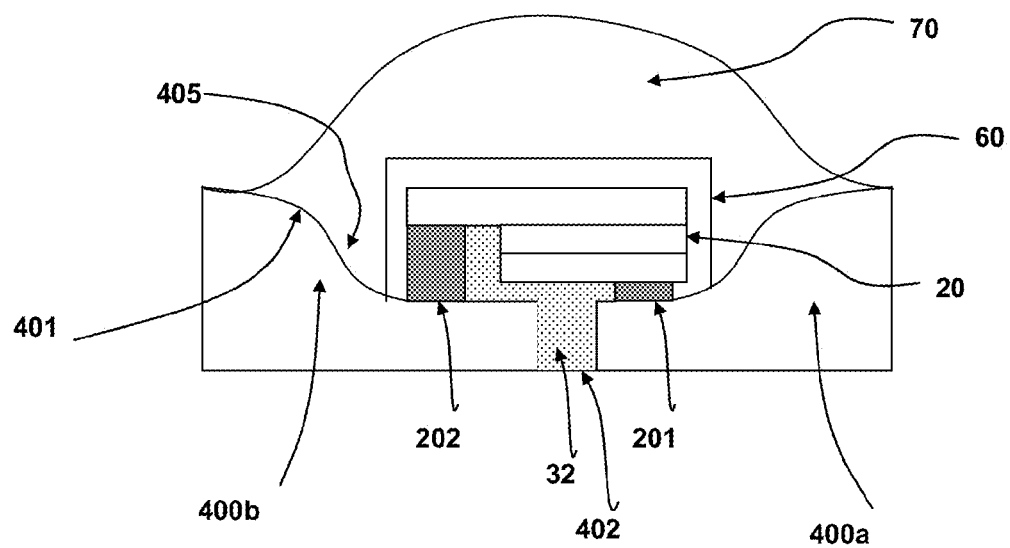


FIG. 2B

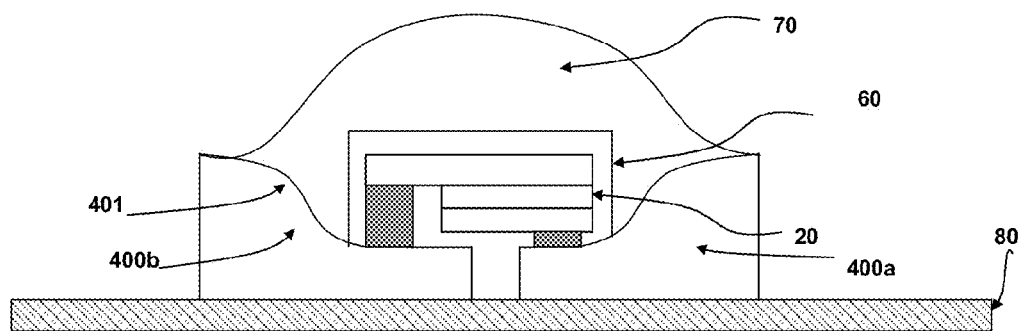


FIG. 3A

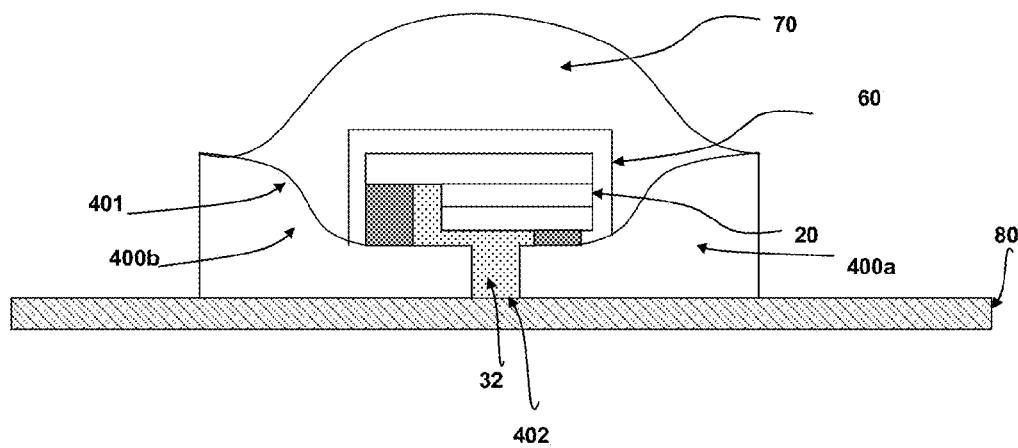


FIG. 3B

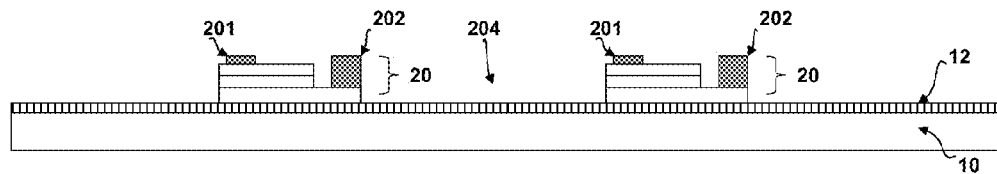


FIG. 4A

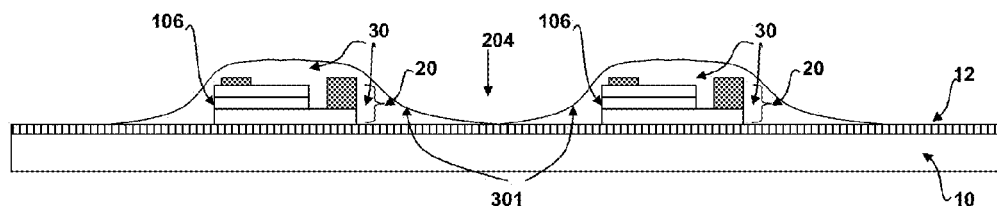


FIG. 4B

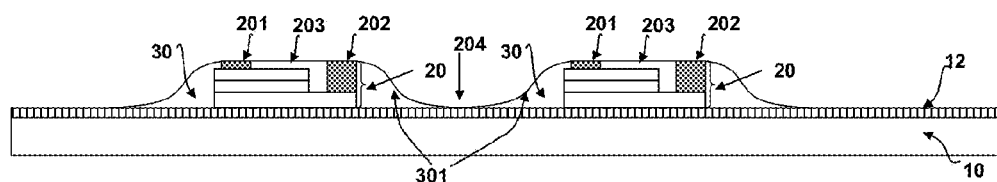


FIG. 4C

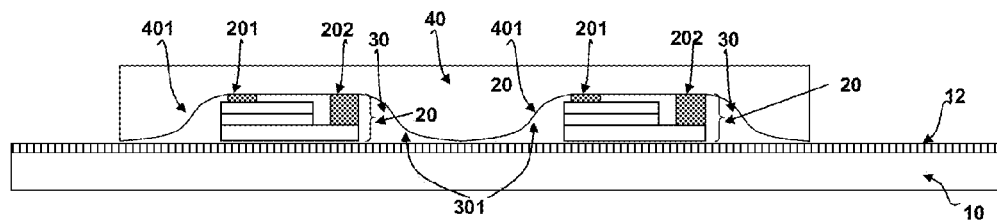


FIG. 4D

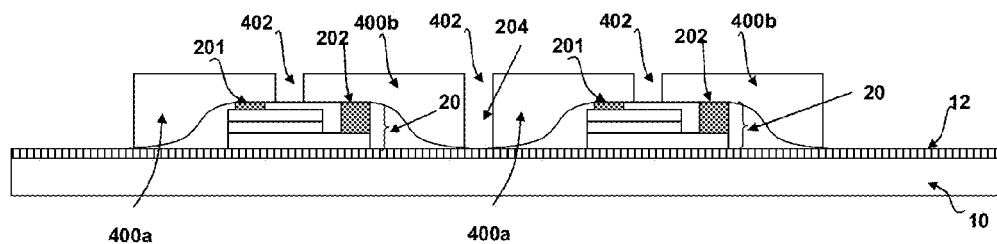


FIG. 4E

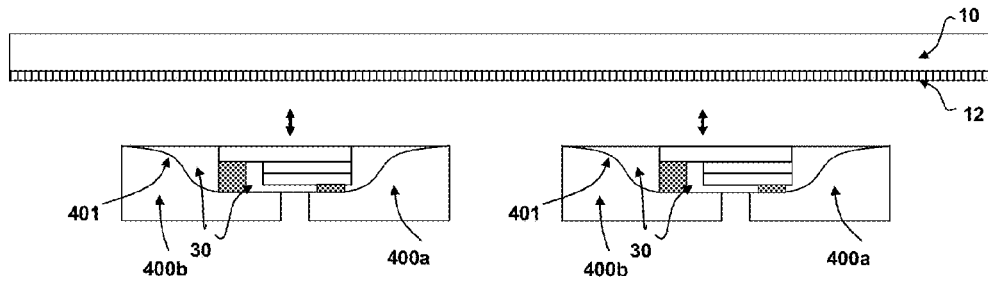


FIG. 4F

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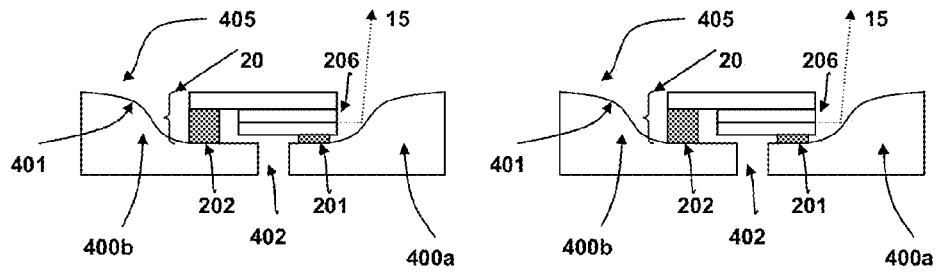


FIG. 4G

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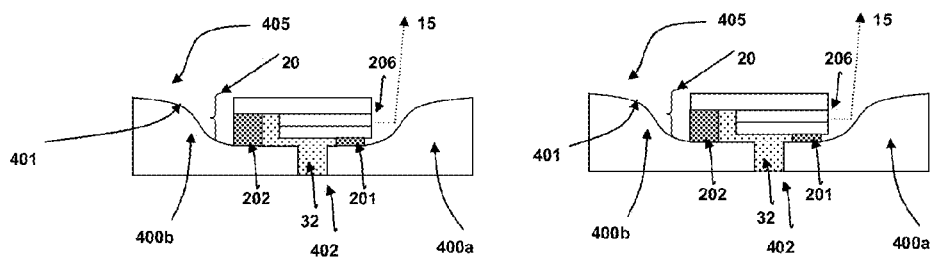


FIG. 4H

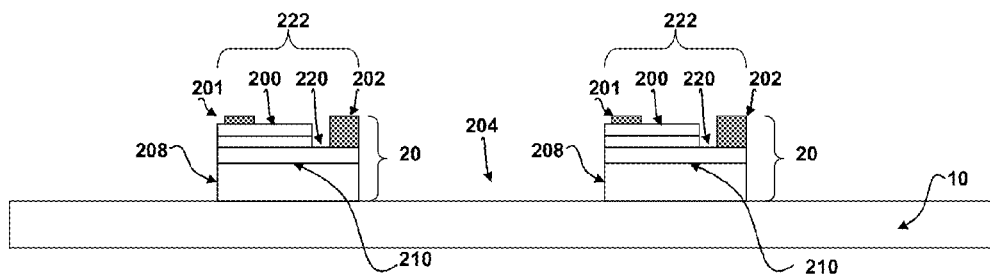


FIG. 5A

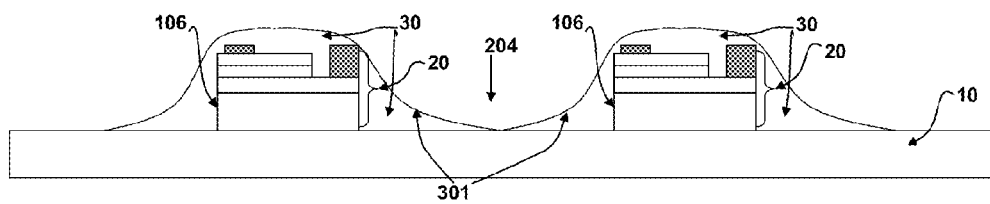


FIG. 5B

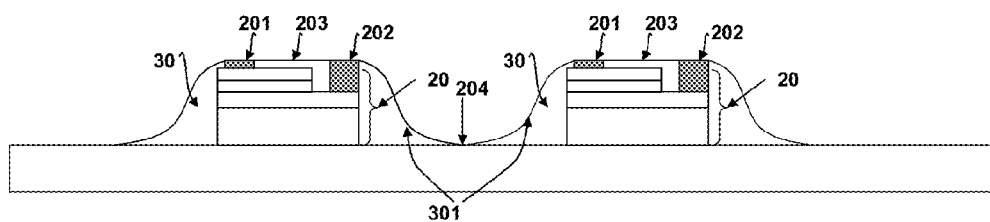


FIG. 5C

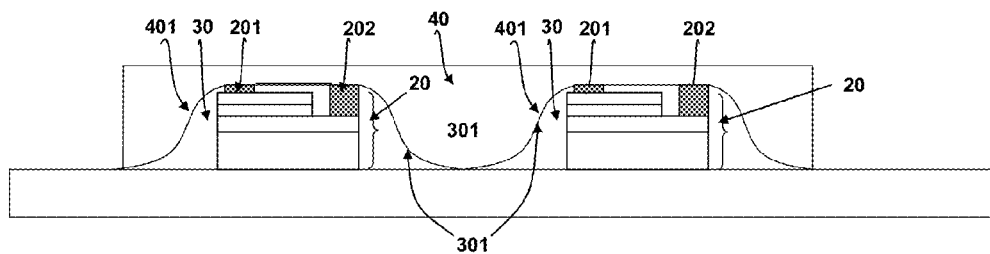


FIG. 5D

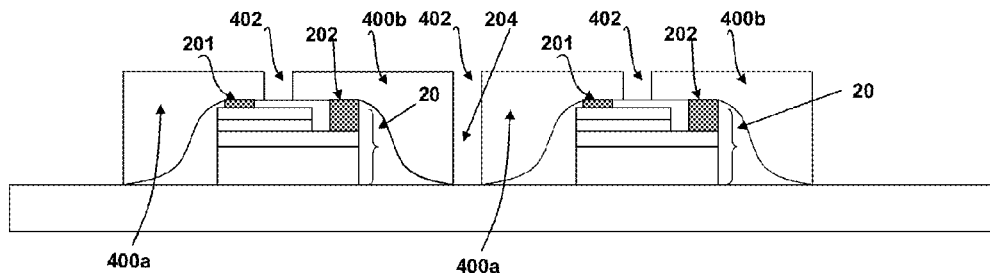


FIG. 5E

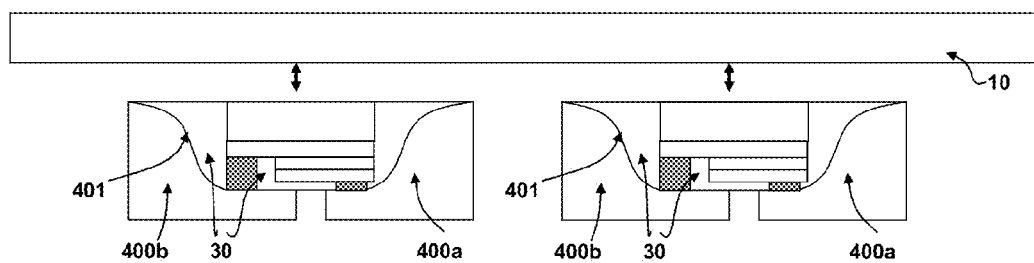


FIG. 5F

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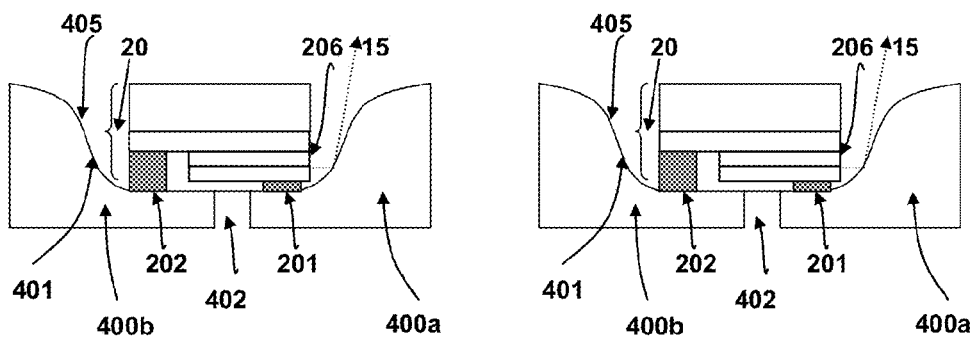


FIG. 5G

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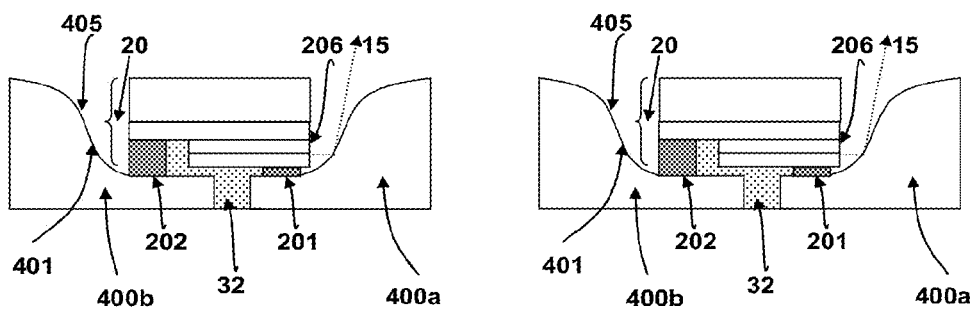


FIG. 5H

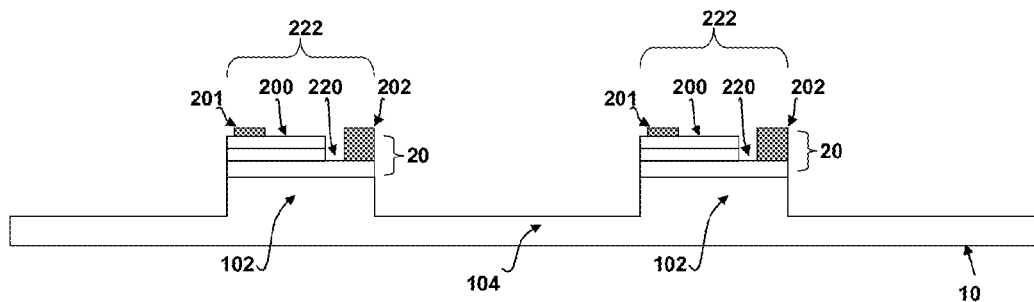


FIG. 6A

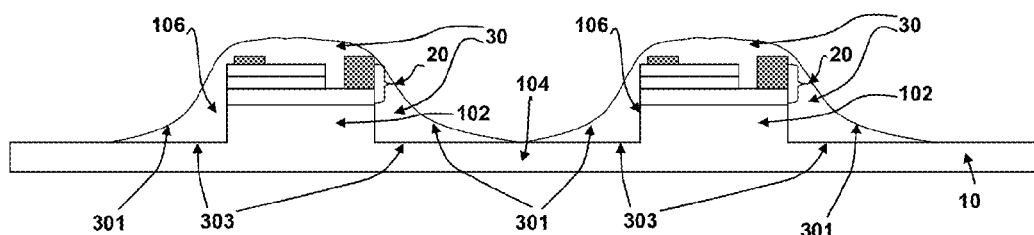


FIG. 6B

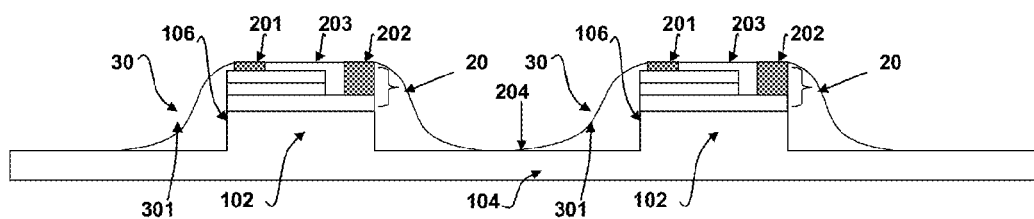


FIG. 6C

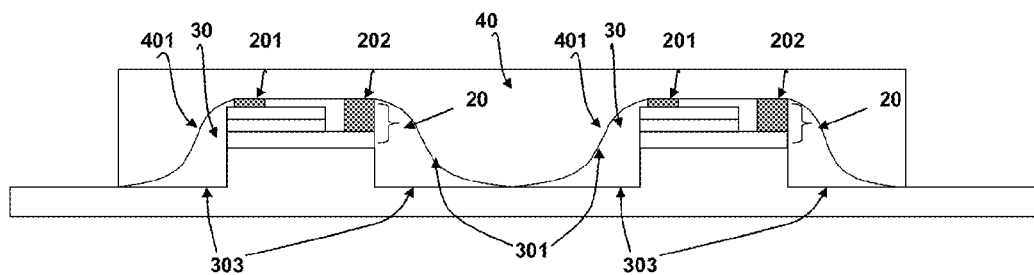


FIG. 6D

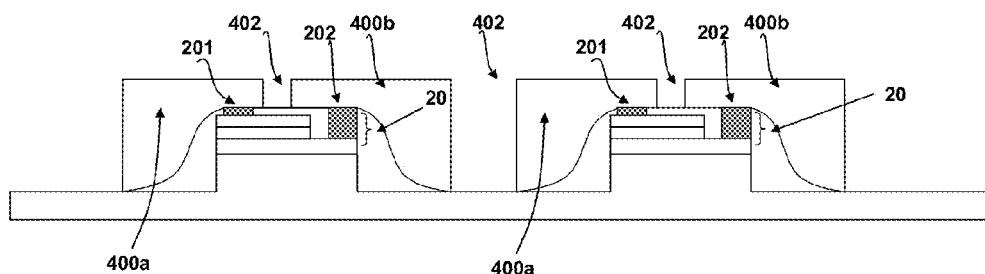


FIG. 6E

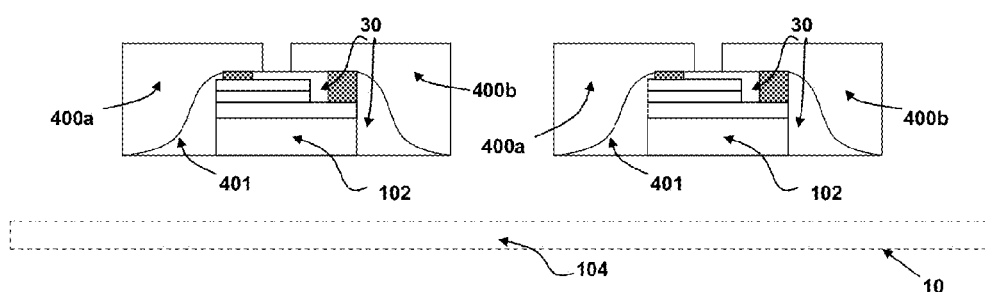


FIG. 6F

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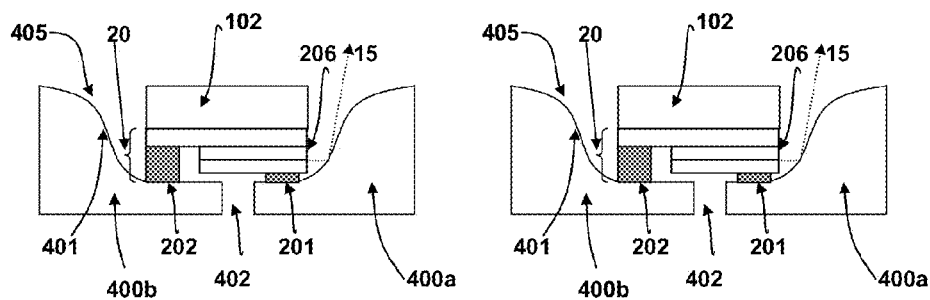


FIG. 6G

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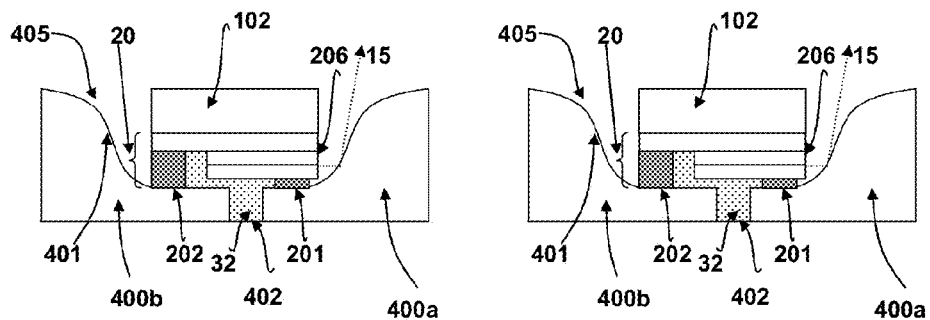


FIG. 6H

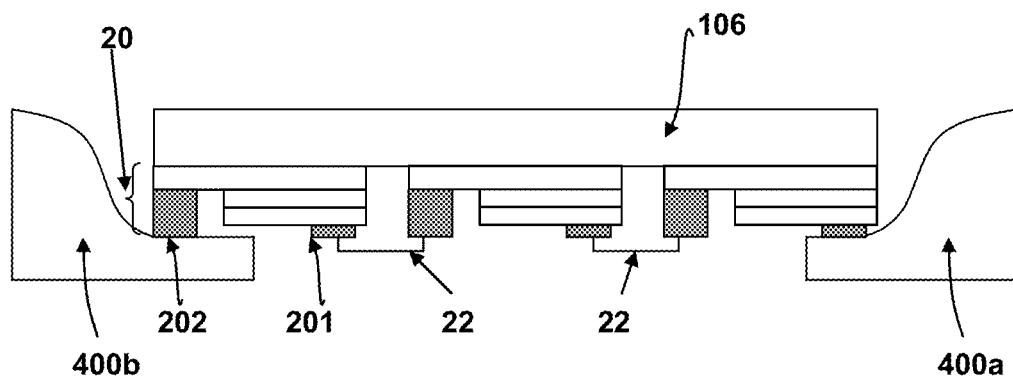


FIG. 7

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LIGHT EMITTING STRUCTURE HAVING ELECTRODES FORMING A CONCAVE SURFACE AND MANUFACTURING METHOD THEREOF

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a Continuation of U.S. application Ser. No. 13/227,841, filed Sep. 8, 2011, which claims the right of priority based on Taiwan patent application Ser. No. 099130428, filed Sep. 8, 2010, and the content of which is hereby incorporated by reference in its entirety.

TECHNICAL FIELD

The present application relates to a light-emitting structure and a method of making the same. The light-emitting structure includes a semiconductor light-emitting element and electrodes. To improve a light extraction efficiency of the light-emitting element, the electrodes can form a concave which reflects the light emitted by the semiconductor light-emitting element.

DESCRIPTION OF BACKGROUND ART

In a commonly-known process of making a light-emitting structure, a chip of a light-emitting element such as a light-emitting diode (LED) is made by dicing a finished epitaxial structure formed by an epitaxial growth process. The chip is then arranged on a submount, which is a lead frame or a big size mounting substrate, for the following wire-bonding, soldering, phosphor-coating, and encapsulation processes. However, there are too many steps in these processes. Consequently, the time and the cost of the manufacture are dramatically increased.

SUMMARY OF THE DISCLOSURE

The application discloses a light-emitting structure which includes a semiconductor light-emitting element, a first connection point and a second connection point wherein the first connection point and the second connection point are located at the same side of the semiconductor light-emitting element. The light-emitting structure further includes a first electrode electrically connected to the first connection point and a second electrode electrically connected to the second connection point wherein the first electrode and the second electrode form a concave to accommodate the light emitting element.

The application also discloses a method of manufacturing a light-emitting structure. The method includes steps of providing a carrier; providing a plurality of semiconductor light-emitting elements on the carrier; forming a glue layer on a side wall of each of the semiconductor light emitting elements, wherein the glue layer has a surface; forming a metal layer on the glue layer and the semiconductor light-emitting elements, wherein the metal layer has a corresponding surface facing the surface; patterning the metal layer for forming a plurality of grooves and a plurality of electrodes corresponding to the semiconductor light-emitting elements; and removing the carrier.

BRIEF DESCRIPTION OF THE DRAWINGS

FIGS. 1A~1H illustrate a manufacturing process in accordance with the first embodiment of the present application;

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FIGS. 2A and 2B illustrate a structure of an LED in accordance with the second embodiment of the present application;

FIGS. 3A and 3B illustrate a structure of an LED in accordance with the third embodiment of the present application;

FIGS. 4A~4H illustrate a manufacturing process in accordance with the forth embodiment of the present application;

FIGS. 5A~5H illustrate a manufacturing process in accordance with the fifth embodiment of the present application;

FIGS. 6A~6H illustrate a manufacturing process in accordance with the sixth embodiment of the present application;

FIG. 7 illustrates a structure in accordance with the seventh embodiment of the present application.

DESCRIPTION OF EMBODIMENTS

The application discloses a light-emitting structure and a method of making the light-emitting structure.

Embodiment 1

FIGS. 1A~1H are schematic diagrams showing the structures in accordance with one embodiment of the present application. As shown in FIG. 1A, a carrier 10, on which several semiconductor light-emitting element 20 are arranged, is provided. There is a gap 204 between the semiconductor light-emitting elements 20. The semiconductor light-emitting elements 20 can emit lights having identical or different wavelength(s) ranged between ultraviolet and infrared. The semiconductor light-emitting element 20 can be a light-emitting diode having an upper surface 200, on which a first connection point 201 is arranged, and a down surface 220 on which a second connection point 202 is arranged, wherein the upper surface and the down surface are on the same side 222 of the light-emitting element 20. The semiconductor light-emitting element 20 can emit light when the current is injected through the first and the second connection points. The carrier 10 can be a growth substrate, such as sapphire, SiC, ZnO, GaN, AlN, or GaAs, for growing the semiconductor light-emitting element 20. The semiconductor light-emitting elements 20 can be formed on the carrier 10 by a conventional semiconductor growth technology.

Then, as shown in FIG. 1B, a glue layer 30 is formed on the gap 204 wherein the glue layer 30 is mainly formed on the side wall 106 of the semiconductor light-emitting element 20 to form a surface 301. The glue layer 30 can be formed by spin coating, printing, or molding glue filling, and the material of the glue layer 30 can be elastic material such as silicone rubber, silicon resin, silicone gel, elastic PU, porous PU, or acrylic rubber; or dies-cutting glue such as blue film and UV glue. During the process of forming the glue layer 30, some glue layer 30 may cover the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20. In that case, the first connection point 201 and the second connection point 202 of the semiconductor light-emitting elements 20 can be exposed by polishing process to remove the glue layer 30 as shown in FIG. 1C.

Next, as shown in FIG. 1D, a metal layer 40 is formed on the glue layer 30 and the semiconductor light-emitting elements 20. The metal layer 40 can be formed by plating, evaporation, or sputtering, and can be the material with conductivity and high reflectivity, such as copper (Cu), aluminum (Al), gold (Au), silver (Ag) or other alloys. Since the formation of the metal layer 40 follows the topography of the below structure, the metal layer 40 contacting with the glue layer 30 forms a corresponding surface 401 along the

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surface 301 of the glue layer 30, and contacts with the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20, wherein the corresponding surface 401 can be a curved surface, a beveled surface, or the combination of a partial curved surface and a partial beveled surface.

Then, as shown in FIG. 1E, the metal layer 40 can be patterned to form a plurality of grooves 402 by photolithography and etching, wherein the grooves 402 on the semiconductor light-emitting element 20 can divide the metal layer 40 on the semiconductor light-emitting element 20 into a first electrode 400a and a second electrode 400b. The first electrode 400a is electrically connected to the first connection point 201, and the second electrode 400b is electrically connected to the second connection point 202. The groove 402 upon the gap 204 can electrically isolate the two adjacent semiconductor light-emitting elements 20.

In another embodiment, after the polishing process as shown in FIG. 1C, the first electrode 400a and the second electrode 400b can also be formed by the process of forming a patterned photoresist to cover the gap 204 and the second surface 203 between the first connection point 201 and the second connection point 202, and then electroplating metal material on the surface 301, the first connection point 201 and the second connection point 202, and then removing the patterned photoresist.

Then, as shown in FIG. 1F, the carrier 10 can be removed by laser lift-off, etching, or other methods. Finally, the glue layer 30 is removed as shown in FIG. 1G to exposes the corresponding surface 401 of the first electrode 400a and the second electrode 400b. A plurality of light-emitting structures 50 is formed accordingly. It should be noted that since the first electrode 400a and the second electrode 400b of the light-emitting structure 50 are conductive, the external current is injected into the semiconductor light-emitting element 20 through the first connection point 201 and the second connection point 202 to generate light. Therefore, there is no need to connect wires to the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20 by photolithography wire or wire bonding. Since the corresponding surface 401 of the first electrode 400a and the second electrode 400b forms a concave 405, which is a metal surface for reflection, as the semiconductor light-emitting element 20 located on the concave 405 emits a light 15 (the dashed line) from a light-emitting side 206 of the semiconductor light-emitting element 20, the corresponding surface 401 can reflect the light 15 to improve overall light extraction efficiency. And, as shown in FIG. 1H, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202.

Embodiment 2

Next, as shown in FIG. 2A, the semiconductor light-emitting element 20 further can be covered by a wavelength conversion layer 60, wherein the wavelength conversion layer 60 can be formed by spin coating, deposition, dispensing, scraper, or molding glue filling. The wavelength conversion layer 60 includes at least one material which is blue phosphor, yellow phosphor, green phosphor, red phosphor, ZnSe, ZnCdSe, III-phosphide, III-arsenide, or the combination of III-nitride. The blue phosphor can convert the light to blue light, and the others like yellow phosphor, green phosphor, and red phosphor have the similar function. The

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material and the combination of any kinds of phosphor are conventional art and are not explained here. The wavelength conversion layer 60 converts all or partial of the light with a first wavelength emitted from the semiconductor light-emitting element 20 to a light with a second wavelength. After forming the wavelength conversion layer 60, an encapsulation layer 70 can also be formed on the light-emitting structure 50 by dispensing. The encapsulation layer 70 can be designed as a structure having a function of lens to improve light extraction efficiency. And, as shown in FIG. 2B, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202.

Embodiment 3

FIG. 3A shows another embodiment of the present application indicating the encapsulated light-emitting structure 50 disclosed in FIG. 2A is located upon a sub-carrier 80. The sub-carrier 80 can be a printed circuit board or a carrier with via plug. A control signal is transmitted into the light-emitting structure 50 via the sub-carrier 80 with the designed circuit. The light-emitting structure 50 can be welded on the sub-carrier 80 by the high-frequency welding process and so on. And, as shown in FIG. 3B, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with an insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202.

Embodiment 4

FIGS. 4A~4H are schematic diagrams in accordance with another embodiment of the present application. As shown in FIG. 4A, a carrier 10 is provided, and a connecting layer 12 is formed on the carrier 10 by spin coating, evaporation, or printing, wherein the upper and lower surfaces of the connecting layer 12 have adhesion to fix a plurality of semiconductor light-emitting elements 20 on the carrier 10. There is a plurality of gaps 204 between the semiconductor light-emitting elements 20. The plurality of the semiconductor light-emitting elements 20 can emit lights having the same or different wavelengths ranged from ultraviolet to infrared ray. The semiconductor light-emitting element 20 can be a light-emitting diode having a first connection point 201 and a second connection point 202 for the current injection for emitting light. The carrier 10 can be a temporary substrate, and the plural semiconductor light-emitting elements 20 can be produced elsewhere and then be transferred to the carrier 10. The material of the carrier 10 can be silicone rubber, glass, quartz, ceramic, or alloys.

Then, as shown in FIG. 4B, a glue layer 30 is formed on the gap 204 wherein the glue layer 30 is mainly formed on the side wall 106 of the semiconductor light-emitting element 20 to form a surface 301. The glue layer 30 can be formed by spin coating, printing, or molding glue filling, and the material of the glue layer 30 can be elastic material such as silicone rubber, silicon resin, silicone gel, elastic PU, porous PU, acrylic rubber; or dies-cutting glue such as blue film and UV glue. During the process of forming the glue layer 30, part of the glue layer 30 may cover the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20. In that case, the first connection point 201 and the second connection point 202 of the semiconductor light-emitting elements 20

can be exposed by polishing process to remove the glue layer 30 as shown in FIG. 4C.

Next, as shown in FIG. 4D, a metal layer 40 is formed on the glue layer 30 and the semiconductor light-emitting elements 20. The metal layer 40 can be formed by plating, evaporation, or sputtering, and can be the material with conductivity and high reflectivity, such as copper (Cu), aluminum (Al), gold (Au), silver (Ag) or other alloys. Since the formation of the metal layer 40 follows the topography of the below structure, the metal layer 40 contacting with the glue layer 30 forms a corresponding surface 401 along the surface 301 of the glue layer 30, and contacts with the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20, wherein the corresponding surface 401 can be a curved surface, a beveled surface, or the combination of a partial curved surface and a partial beveled surface.

Then, as shown in FIG. 4E, the metal layer 40 can be patterned to form a plurality of grooves 402 by photolithography and etching, wherein the grooves 402 on the semiconductor light-emitting element 20 can divide the metal layer 40 on the semiconductor light-emitting elements 20 into a first electrode 400a and a second electrode 400b. The first electrode 400a is electrically connected to the first connection point 201, and the second electrode 400b is electrically connected to the second connection point 202. The groove 402 upon the gap 204 can electrically isolate the two adjacent semiconductor light-emitting elements 20.

In another embodiment, after the polishing process as shown in FIG. 4C, the first electrode 400a and the second electrode 400b can also be formed by the process of forming a patterned photoresist to cover the gap 204 and the second surface 203 between the first connection point 201 and the second connection point 202, and then electroplating metal material on the surface 301, the first connection point 201 and the second connection point 202, and then removing the patterned photoresist.

Then, as shown in FIG. 4F, the carrier 10 and the connecting layer 12 can be removed by laser lift-off, etching, or other methods. Finally, the glue layer 30 is removed as shown in FIG. 4G to exposes the corresponding surface 401 of the first electrode 400a and the second electrode 400b. A plurality of light-emitting structures 50 is formed accordingly. It should be noted that since the first electrode 400a and the second electrode 400b of the light-emitting structure 50 are conductive, the external current is injected into the semiconductor light-emitting element 20 through the first connection point 201 and the second connection point 202 to generate light. Therefore, there is no need to connect wires to the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20 by photolithography wire and wire bonding. Since the corresponding surface 401 of the first electrode 400a and the second electrode 400b forms a concave 405, which is a metal surface for reflection, as the semiconductor light-emitting element 20 located on the concave 405 emits a light 15 (the dashed line) from a light-emitting side 206 of the semiconductor light-emitting element 20, the corresponding surface 401 can reflect the light 15 to improve overall light extraction efficiency. And, as shown in FIG. 4H, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with an insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202.

Embodiment 5

FIGS. 5A—5H are schematic diagrams showing the structures in accordance with another embodiment of the present application. As shown in FIG. 5A, a carrier 10, on which several semiconductor light-emitting elements 20 are arranged, is provided. There is a gap 204 between the semiconductor light-emitting elements 20. The semiconductor light-emitting elements 20 can emit lights having the same or different wavelength(s) ranged between ultraviolet and infrared. The semiconductor light-emitting element 20 can be a light-emitting diode having an upper surface 200, on which a first connection point 201 is arranged, a down surface 220, on which a second connection point 202 is arranged, and a base 208. The upper surface and the down surface are on the same side 222 of the semiconductor light-emitting element 20. The material of the base can be transparent material such as Sapphire, Diamond, Glass, Epoxy, Quartz, Acryl, ZnO, or AlN. The semiconductor light-emitting element 20 can emit light when the current is injected through the first and the second connection points. The carrier 10 can be a growth substrate, such as sapphire, SiC, ZnO, GaN, AlN, or GaAs, for growing the semiconductor light-emitting element 20. The semiconductor light-emitting elements 20 can be formed on the carrier 10 by a conventional semiconductor growth technology.

Then, as shown in FIG. 5B, a glue layer 30 is formed on the gap 204 wherein the glue layer 30 is mainly formed on the side wall 106 of the semiconductor light-emitting element 20 to form a surface 301. The glue layer 30 can be formed by spin coating, printing, or molding glue filling and the material of the glue layer 30 can be elastic material such as silicone rubber, silicon resin, silicone gel, elastic PU, porous PU, or acrylic rubber; or dies-cutting glue such as blue film and UV glue. During the process of forming the glue layer 30, some glue layer 30 may cover the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20. In that case, the first connection point 201 and the second connection point 202 of the semiconductor light-emitting elements 20 can be exposed by polishing process to remove the glue layer 30 as shown in FIG. 5C.

Next, as shown in FIG. 5D, a metal layer 40 is formed on the glue layer 30 and the semiconductor light-emitting elements 20. The metal layer 40 can be formed by plating, evaporation, or sputtering, and can be the material with conductivity and high reflectivity, such as copper (Cu), aluminum (Al), gold (Au), silver (Ag) or other alloys. Since the formation of the metal layer 40 follows the topography of the below structure, the metal layer 40 contacting with the glue layer 30 forms a corresponding surface 401 along the surface 301 of the glue layer 30, and contacts with the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20, wherein the corresponding surface 401 can be a curved surface, a beveled surface, or the combination of a partial curved surface and a partial beveled surface.

Then, as shown in FIG. 5E, the metal layer 40 can be patterned to form a plurality of grooves 402 by photolithography and etching, wherein the grooves 402 on the semiconductor light-emitting element 20 can divide the metal layer 40 on the semiconductor light-emitting elements 20 into the first electrodes 400a and the second electrodes 400b. The first electrode 400a is electrically connected to the first connection point 201, and the second electrode 400b is electrically connected to the second connection point 202. The groove 402 upon the gap 204 can electrically isolate the two adjacent semiconductor light-emitting elements 20.

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In another embodiment, after the polishing process as shown in FIG. 5C, the first electrode 400a and the second electrode 400b can also be formed by the process of forming a patterned photoresist to cover the gap 204 and the second surface 203 between the first connection point 201 and the second connection point 202, and then electroplating metal material on the surface 301, the first connection point 201 and the second connection point 202, and then removing the patterned photoresist.

Then, as shown in FIG. 5F, the carrier 10 can be removed by laser lift-off, etching, or other methods. Finally, the glue layer 30 is removed as shown in FIG. 5G to exposes the corresponding surfaces 401 of the first electrode 400a and the second electrode 400b. A plurality of light-emitting structures 50 is formed accordingly. It should be noted that since the first electrode 400a and the second electrode 400b of the light-emitting structure 50 are conductive, the external current is injected into the semiconductor light-emitting element 20 through the first connection point 201 and the second connection point 202 to generate light. Therefore, there is no need to connect wires to the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20 by photolithography wire or wire bonding. Since the corresponding surface 401 of the first electrode 400a and the second electrode 400b forms a concave 405 which is a metal surface for reflection, as the semiconductor light-emitting element 20 located on the concave 405 emits a light 15 (the dashed line) from a light-emitting side 206 of the semiconductor light-emitting element 20, the corresponding surface 401 can reflect the light 15 to improve overall light extraction efficiency. And, as shown in FIG. 5H, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with an insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202.

Embodiment 6

FIGS. 6A~6H are schematic diagrams showing the structures in accordance with the sixth embodiment of the present application. As shown in FIG. 6A, a carrier 10 which has a plurality of convex portions 102 and a plurality of channel portions 104 is provided. Several semiconductor light emitting elements 20 are arranged on the convex portions 102 correspondingly. The semiconductor light-emitting elements 20 can emit lights having the same or different wavelength (s) ranged between ultraviolet and infrared. The semiconductor light-emitting element 20 can be a light-emitting diode having an upper surface 200, on which a first connection point 201 is arranged, and a down surface 220, on which a second connection point 202 is arranged, wherein the upper surface and the down surface are on the same side 222 of the light-emitting element 20. The semiconductor light-emitting element 20 can emit light when the current is injected through the first and the second connection points. The carrier 10 can be a growth substrate, such as sapphire, SiC, ZnO, GaN, AlN, or GaAs, for growing the semiconductor light-emitting element 20. The semiconductor light-emitting elements 20 can be formed on the carrier 10 by a conventional semiconductor growth technology.

Then, as shown in FIG. 6B, a glue layer 30 is formed on the channel portions 104 wherein the glue layer 30 is mainly formed on the side wall 106 of the semiconductor light-emitting element 20 to form a surface 301. The glue layer 30 can be formed by spin coating, printing, or molding glue filling and the material of the glue layer 30 can be elastic

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material such as silicone rubber, silicon resin, silicone gel, elastic PU, porous PU, or acrylic rubber; or dies-cutting glue such as blue film and UV glue. During the process of forming the glue layer 30, some glue layer 30 may cover the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20. In that case, the first connection point 201 and the second connection point 202 of the semiconductor light-emitting elements 20 can be exposed by polishing process to remove the glue layer 30 as shown in FIG. 6C.

Next, as shown in FIG. 6D, a metal layer 40 is formed on the glue layer 30 and the semiconductor light-emitting elements 20. The metal layer 40 can be formed by plating, evaporation, or sputtering, and can be the material with conductivity and high reflectivity, such as copper (Cu), aluminum (Al), gold (Au), silver (Ag) or other alloys. Since the formation of the metal layer 40 follows the topography of the below structure, the metal layer 40 contacting with the glue layer 30 forms a corresponding surface 401 along the surface 301 of the glue layer 30, and contacts with the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20, wherein the corresponding surface 401 can be a curved surface, a beveled surface, or the combination of a partial curved surface and a partial beveled surface.

Then, as shown in FIG. 6E, the metal layer 40 can be patterned to form a plurality of grooves 402 by photolithography and etching, wherein the grooves 402 on the semiconductor light-emitting element 20 can divide the metal layer 40 on the semiconductor light-emitting elements 20 into the first electrodes 400a and the second electrodes 400b. The first electrode 400a is electrically connected to the first connection point 201, and the second electrode 400b is electrically connected to the second connection point 202. The groove 402 upon the gap 204 can electrically isolate the two adjacent semiconductor light-emitting elements 20.

In another embodiment, after the polishing process as shown in FIG. 6C, the first electrode 400a and the second electrode 400b can also be formed by the process of forming a patterned photoresist to cover the gap 204 and the second surface 203 between the first connection point 201 and the second connection point 202, and then electroplating metal material on the surface 301, the first connection point 201 and the second connection point 202, and then removing the patterned photoresist.

Then, as shown in FIG. 6F, the channel portions 104 of the carrier 10 can be removed by etching or polishing process. Finally, the glue layer 30 is removed as shown in FIG. 6G to exposes the corresponding surfaces 401 of the first electrode 400a and the second electrode 400b. A plurality of light-emitting structures 50 is formed accordingly. It should be noted that since the first electrode 400a and the second electrode 400b of the light-emitting structure 50 are conductive, the external current is injected into the semiconductor light-emitting element 20 through the first connection point 201 and the second connection point 202 to generate light. Therefore, there is no need to connect wires to the first connection point 201 and the second connection point 202 of the semiconductor light-emitting element 20 by photolithography for connector or wire bonding. Since the corresponding surface 401 of the first electrode 400a and the second electrode 400b forms a concave 405, which is a metal surface for reflection, as the semiconductor light-emitting element 20 located on the concave 405 emits a light 15 (the dashed line) from a light-emitting side 206 of the semiconductor light-emitting element 20, the corresponding surface 401 can reflect the light 15 to improve overall light extrac-

tion efficiency. And, as shown in FIG. 6H, the groove 402 among the semiconductor light-emitting element 20, the first electrode 400a, and the second electrode 400b can be filled in with insulating material 32 such as epoxy to enhance the ability of the structure of semiconductor light-emitting element 20 to resist thermal fatigue and protect the first connection point 201 and the second connection point 202. Embodiment 7

Next, as shown in FIG. 7, the semiconductor light-emitting elements 20 further can be connected to form a series connection. The series connection is formed by connecting wires to the first connection point 201 and the second connection point 202 with photolithography wire bonding or wire bonding.

By means of the detail descriptions of what is presently considered to be the most practical and preferred embodiments of the subject invention, it is the expectation that the features and the gist thereof are plainly revealed. Nevertheless, these above-mentioned illustrations are not intended to be construed in a limiting sense. Instead, it should be well understood that any analogous variation and equivalent arrangement is supposed to be covered within the spirit and scope to be protected and that the interpretation of the scope of the subject invention would therefore as much broadly as it could apply.

What is claimed is:

1. A light-emitting structure, comprising:
 - a semiconductor light-emitting element comprising a sidewall, a first connection point, and a second connection point;
 - a glue layer covering the sidewall;
 - a first electrode electrically connected to the first connection point, and comprising a portion with a curved surface, a beveled surface, or a combination thereof; and
 - a second electrode electrically connected to the second connection point,
 wherein the glue layer and the portion are overlapped with each other in a direction substantially parallel to the sidewall.
2. The light-emitting structure of claim 1, further comprising a wavelength conversion layer, an encapsulation layer, or both thereof arranged on the semiconductor light-emitting element.

3. The light-emitting structure of claim 1, wherein the semiconductor light-emitting element comprises a wavelength conversion layer being conformably shaped on the semiconductor light-emitting element.

4. The light-emitting structure of claim 1, further comprising a lens arranged on the semiconductor light-emitting element, and a wavelength conversion layer formed between the lens and the semiconductor light-emitting element.

5. The light-emitting structure of claim 1, wherein the first electrode and the second electrode are separated from each other by a groove.

6. The light-emitting structure of claim 5, further comprising an insulating material filled in the groove.

7. The light-emitting structure of claim 1, wherein the first electrode has an outer thickness and an inner thickness which is thinner than the outer thickness.

8. The light-emitting structure of claim 1, further comprising a growth substrate for epitaxially growing the semiconductor light-emitting element, or a temporary substrate for supporting the semiconductor light-emitting element.

9. The light-emitting structure of claim 1, wherein the semiconductor light-emitting element comprises a base.

10. The light-emitting structure of claim 1, wherein the first electrode has a first side near the semiconductor light-emitting element, and a second side opposite to the first side, the portion locates at the first side.

11. The light-emitting structure of claim 1, wherein the semiconductor light-emitting element is devoid of a growth substrate.

12. The light-emitting structure of claim 1, wherein the first electrode comprises an edge far away from the semiconductor light-emitting element and not overlapping the semiconductor light-emitting element.

13. The light-emitting structure of claim 1, wherein the first electrode comprises a first edge not overlapping the semiconductor light-emitting element, the second electrode comprises a second edge not overlapping the semiconductor light-emitting element, a distance between the first edge and the second edge is larger than a width of the semiconductor light-emitting element.

14. The light-emitting structure of claim 1, further comprising a groove formed between the first electrode and the second electrode, wherein the first electrode has a portion higher than the groove.

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